RX Family and M16C Family

Guide for Migration from the M16C to the RX: External Bus

Abstract

This document describes migration from the external bus in the M16C Family to the external bus in the RX Family.

Products

RX Family

M16C Family

When this document explains migration from the M16C Family to the RX Family, the M16C/65C Group MCU is used as an example of the M16C Family MCU, and the RX231 Group and RX660 Group MCUs are used as examples of the RX Family MCU. When using this application note with other Renesas MCUs, careful evaluation is recommended after making modifications to comply with the alternate MCU.

Differences in Terminology Between the RX Family and M16C Family MCUs

Item	M16C Family	RX Family
Operating mode to access the external memory device	• Memory expansion mode • Microprocessor mode	• On-chip ROM enabled expansion mode • On-chip ROM disabled expansion mode
External memory area	External area	External address space CSn area
Peripheral function registers	Special function registers (SFRs)	I/O registers

Contents

1. Functional Differences in the External Bus

Table 1.1 shows Functional Differences in the External Bus.

Table 1.1 Functional Differences in the External Bus

Item	M16C (M16C/65C)	RX (RX231)	RX (RX660)
Memory size	1 MB/4 MB	16 MB	2 MB
Bus type	Separate bus/multiplexed bus	Separate bus/multiplexed bus	Separate bus/multiplexed bus
Data bus width	8-bit/16-bit	8-bit/16-bit	8-bit/16-bit
Data bus width setting	Set using the BYTE pin	Set using the CSn control register (n = 0 to 3)	Set using the CSn control register (n = 0 to 3)
Address buses	12, 16, or 20 buses selectable	8 to 24 buses selectable	8 to 21 buses selectable
Chip select outputs	4	4	4
Write access mode	Write signal combinations • BHE/WR • WRL/WRH	1-write strobe mode Byte strobe mode	1-write strobe mode Byte strobe mode
Wait cycle	RDY pin	WAIT pin	WAIT pin
Software wait	0 to 8 waits can be inserted (selectable from 1ϕ + 1ϕ, 1ϕ + 2ϕ, 1ϕ + 3ϕ, 2ϕ + 3ϕ, 2ϕ + 4ϕ, 3ϕ + 4ϕ, or 4ϕ + 5ϕ)	Wait for up to 31 cycles	Wait for up to 31 cycles
Recovery cycle	0 to 3 cycles inserted (retain the last accessed address for address output)	Maximum of 15 cycles can be inserted (selectable from 8 patterns)	Maximum of 15 cycles can be inserted (selectable from 8 patterns)
Page access	—	Supported	Supported

From this point forward, the application note describes a separate bus.

1.1 Example of Connecting to an External Bus

Connecting to bus pins on the M16C and RX is the same. However, note that pin names for the bus control pins differ.

Figure 1.1 shows Example of Bus Connection When the Bus Width is 16 Bits. Figure 1.2 shows Example of Bus Connection When the Bus Width is 8 Bits.

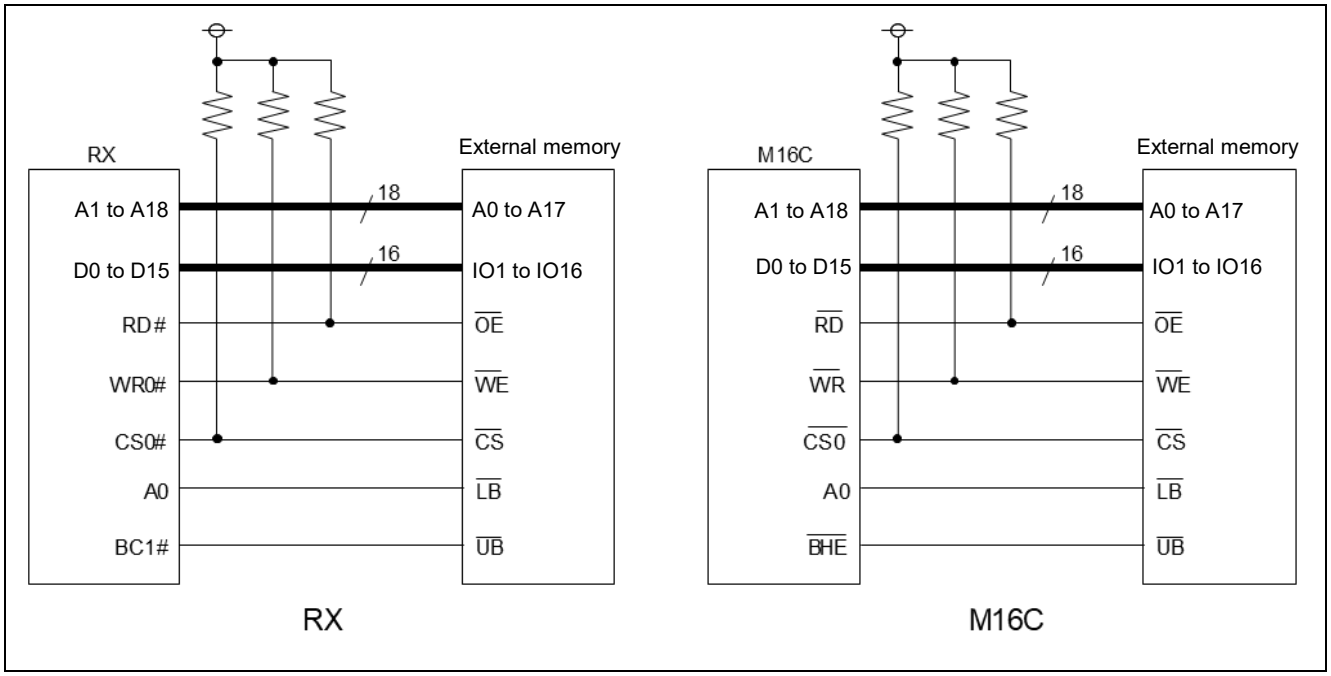


Figure 1.1 Example of Bus Connection When the Bus Width is 16 Bits

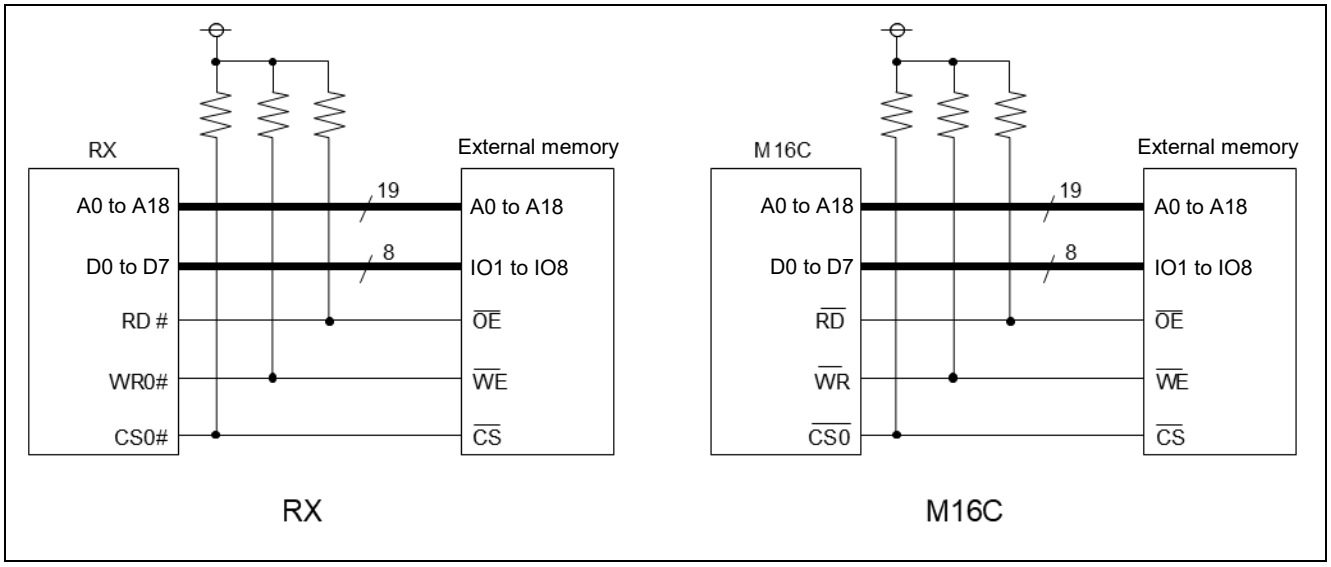


Figure 1.2 Example of Bus Connection When the Bus Width is 8 Bits

1.2 Calculating the Number of Bus Cycles

1.2.1 Calculating the Number of Bus Cycles When Reading

This section shows the differences in the bus timings to be set based on the timing chart in Figure 1.3 Example of Basic Bus Timings (During a Read Operation) between the M16C and the RX.

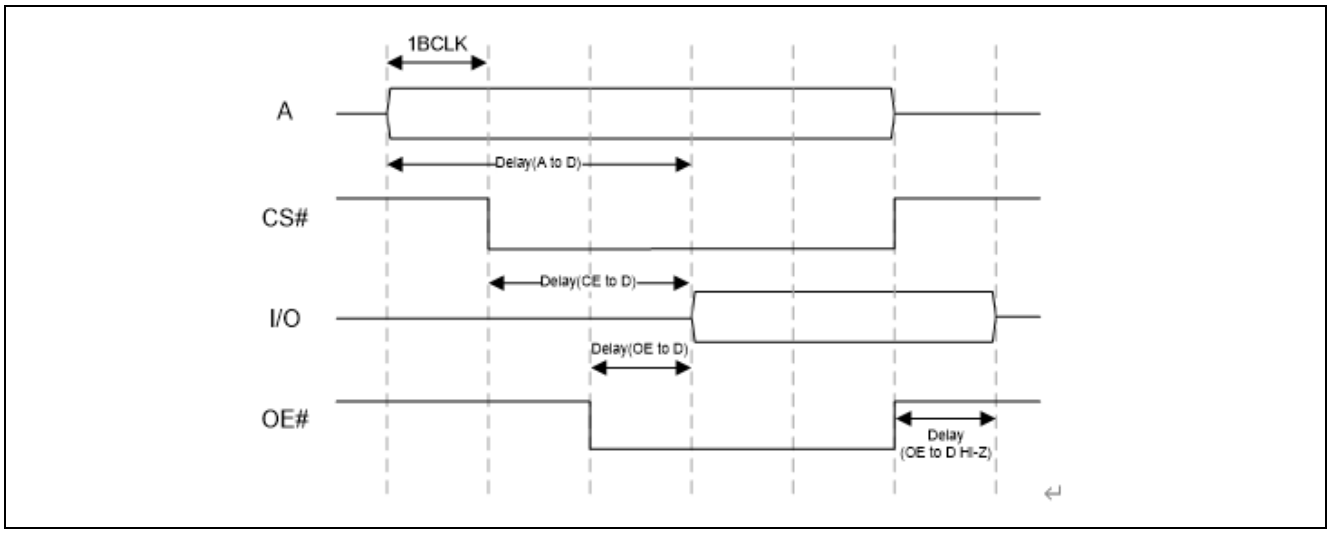
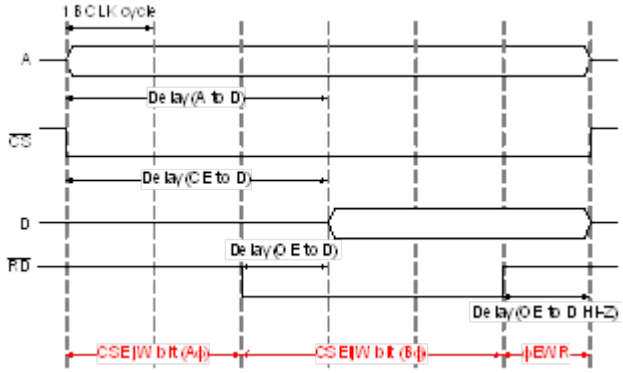
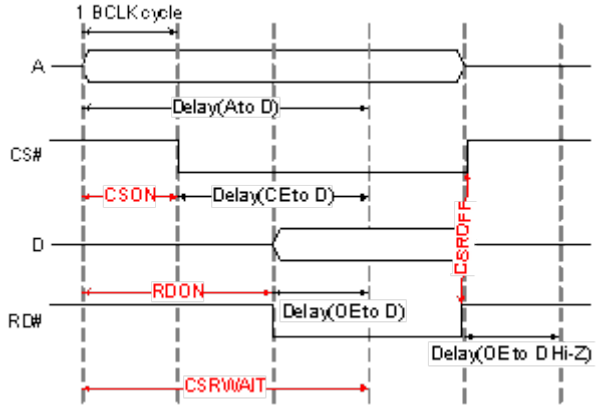


Figure 1.3 Example of Basic Bus Timings (During a Read Operation)

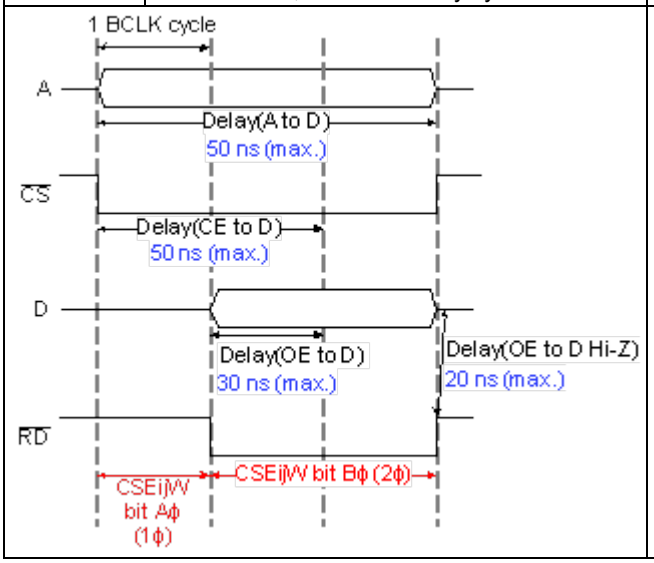
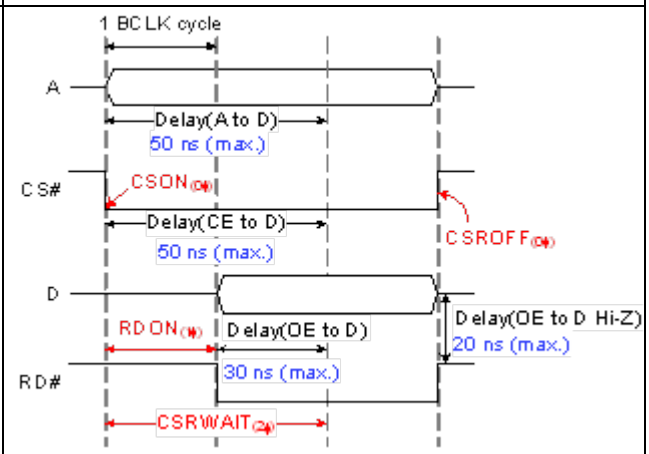
Table 1.2 Differences in the Bus Timing Settings (During a Read Operation)

<table>
<tr><th colspan="2">M16C (M16C/65C)</th><th colspan="2">RX (RX231 or RX660)</th></tr>
<tr><td colspan="2"> 
</td><td colspan="2"> 
</td></tr>
<tr><td colspan="2" rowspan="4">CSEijW bit (Aϕ + Bϕ) (i = 0 to 3, j = 0, 1)
Aϕ sets the number of cycles from the start of the bus access to the falling edge of the RD signal.
Bϕ sets the number of cycles from falling edge of the RD signal to the rising edge.</td><td>CSON</td><td>Sets the number of wait cycles to be inserted before asserting the CSn# signal</td></tr>
<tr><td>RDON</td><td>Sets the number of wait cycles to be inserted before asserting the RD# signal</td></tr>
<tr><td>CSRWAIT</td><td>Sets the number of cycles to be inserted in the first access of the normal read cycle</td></tr>
<tr><td>CSROFF</td><td>Sets the number of cycles from negating the RD# signal during a read access, to negating the CSn# signal</td></tr>
<tr><td>EWR</td><td>Sets the number of recovery cycles according to the number of needed idle cycles</td><td colspan="2">—</td></tr>
</table>

When reading the connected external memory has the following attributes, values set to the M16C and RX registers are shown in Table 1.3.

- Delay (A to D) = 50 ns (max.)
- Delay (CE to D) = 50 ns (max.)
- Delay (OE to D) = 30 ns (max.)
- Delay (OE to D Hi-Z) = 20 ns (max.)

Table 1.3 Differences in the External Bus Register Settings (During a Read Operation When BCLK = 16 MHz)

<table>
<tr><th colspan="2">M16C (M16C/65C)</th><th colspan="2">RX (RX231 or RX660)</th></tr>
<tr><td colspan="2" rowspan="4">CSEijW bit (Aϕ + Bϕ) *1 (i = 0 to 3, j = 0, 1)
CSE = 0x01; /* 2 waits (1ϕ + 2ϕ) */</td><td>CSON</td><td>CS0WCR2.BIT.CSON = 0; *2</td></tr>
<tr><td>RDON</td><td>CS0WCR2.BIT.RDON = 1; *2</td></tr>
<tr><td>CSRWAIT</td><td>CS0WCR1.BIT. CSRWAIT = 2; *2</td></tr>
<tr><td>CSROFF</td><td>CS0WCR2.BIT.CSROFF = 0;</td></tr>
<tr><td>EWR</td><td>EWR = 0x00; / * No recovery cycles */</td><td colspan="2">—</td></tr>
<tr><td colspan="2"> 
</td><td colspan="2"> 
</td></tr>
</table>

Notes: 1. Select from “1ϕ + 1ϕ”, “1ϕ + 2ϕ”, “1ϕ + 3ϕ”, “2ϕ + 3ϕ”, “2ϕ + 4ϕ”, “3ϕ + 4ϕ”, or “4ϕ + 5ϕ”.
2. Satisfy the following condition: CSnWCR2.CSON bit ≤ CSnWCR2.RDON bit ≤ CSnWCR1.CSRWAIT bit.

1.2.2 Calculating the Number of Bus Cycles When Writing

This section shows the differences in the bus timings to be set based on the timing chart in Figure 1.4 Example of Basic Bus Timings (During a Write Operation) between the M16C and the RX.

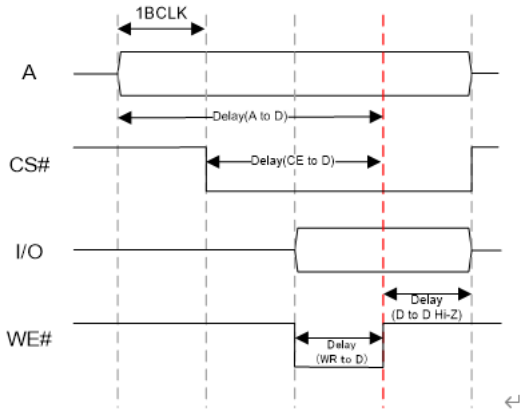
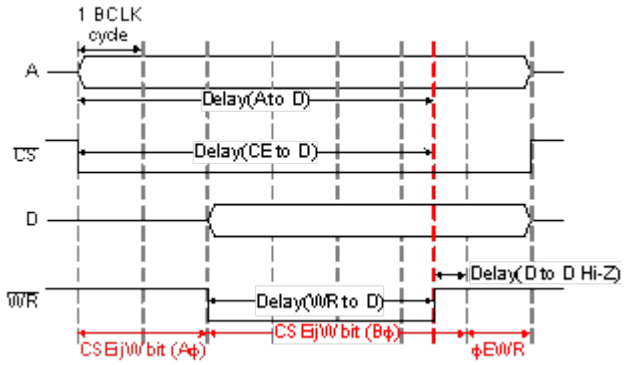
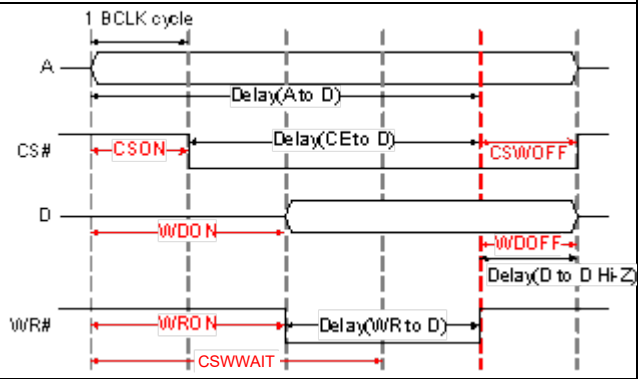


Figure 1.4 Example of Basic Bus Timings (During a Write Operation)

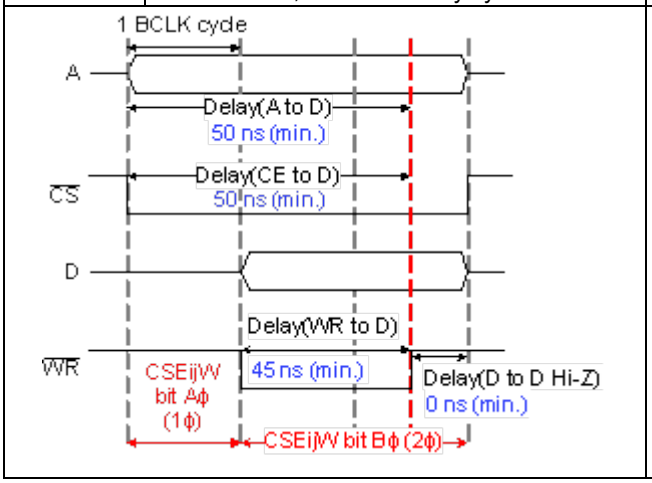
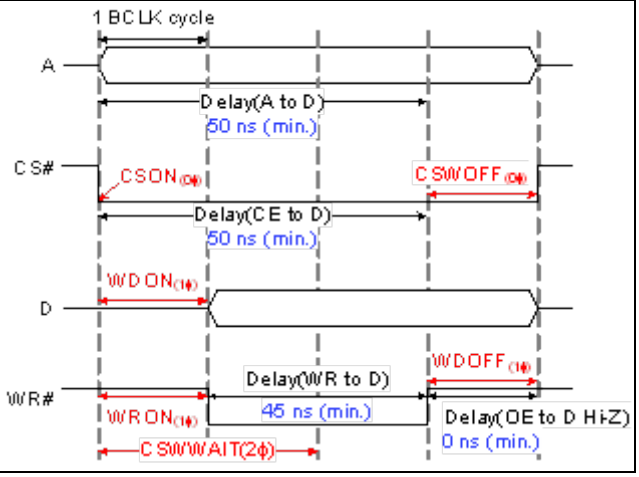
Table 1.4 Differences in the Bus Timing Settings (During a Write Operation)

<table>
<tr><th colspan="2">M16C (M16C/65C)</th><th colspan="2">RX (RX231 or RX660)</th></tr>
<tr><td colspan="2"> 
</td><td colspan="2"> 
</td></tr>
<tr><td colspan="2" rowspan="6">CSEijW bit (Aϕ + Bϕ) (i = 0 to 3, j = 0, 1)
Aϕ sets the number of cycles from the start of the bus access to the falling edge of the WR signal.
Bϕ sets the number of cycles from falling edge of the WR signal to the rising edge.</td><td>CSON</td><td>Sets the number of wait cycles to be inserted before asserting the CSn# signal</td></tr>
<tr><td>WDON</td><td>Sets the number of wait cycles to be inserted before outputting write data</td></tr>
<tr><td>WRON</td><td>Sets the number of wait cycles to be inserted before asserting the WRn# signal</td></tr>
<tr><td>WDOFF</td><td>Sets the number of cycles from negating the WRn# signal during a write access, to write data output completion</td></tr>
<tr><td>CSWWAIT</td><td>Sets the number of cycles to be inserted in the first access of the normal write cycle</td></tr>
<tr><td>CSWOFF</td><td>Sets the number of cycles from negating the WRn# signal during a write access, to negating the CSn# signal</td></tr>
<tr><td>EWR</td><td>Sets the number of recovery cycles according to the number of needed idle cycles</td><td colspan="2">—</td></tr>
</table>

When writing to the connected external memory has the following attributes, values set to the M16C and RX registers are shown in Table 1.5.

- Delay (A to D) = 50 ns (min.)
- Delay (CE to D) = 50 ns (min.)
- Delay (WR to D) = 45 ns (min.)
- Delay (D to D Hi-Z) = 0 ns (min.)

Table 1.5 Differences in the External Bus Register Setting (During a Write Operation When BCLK = 16 MHz)

<table>
<tr><th colspan="2">M16C (M16C/65C)</th><th colspan="2">RX (RX231 or RX660)</th></tr>
<tr><td colspan="2" rowspan="6">CSEijW bit (Aϕ + Bϕ) *1 (i = 0 to 3, j = 0, 1)
CSE = 0x01; /* 2 waits (1ϕ + 2ϕ) */</td><td>CSON</td><td>CS0WCR2.BIT.CSON = 0; *2</td></tr>
<tr><td>WDON</td><td>CS0WCR2.BIT.WDON = 1; *2</td></tr>
<tr><td>WRON</td><td>CS0WCR2.BIT.WRON = 1; *2</td></tr>
<tr><td>WDOFF</td><td>CS0WCR2.BIT.WDOFF = 1; *3</td></tr>
<tr><td>CSWWAIT</td><td>CS0WCR1.BIT.CSWWAIT = 2; *2</td></tr>
<tr><td>CSWOFF</td><td>CS0WCR2.BIT.CSWOFF = 1; *3</td></tr>
<tr><td>EWR</td><td>EWR = 0x00; / * No recovery cycles */</td><td colspan="2">—</td></tr>
<tr><td colspan="2"> 
</td><td colspan="2"> 
</td></tr>
</table>

Notes: 1. Select from “1ϕ + 1ϕ”, “1ϕ + 2ϕ”, “1ϕ + 3ϕ”, “2ϕ + 3ϕ”, “2ϕ + 4ϕ”, “3ϕ + 4ϕ”, or “4ϕ + 5ϕ”.
2. Satisfy the following conditions: 1 ≤ CSnWCR2.WDON bit ≤ CSnWCR2.WRON bit ≤ CSnWCR1.CSWWAIT bit, and CSnWCR2.CSON bit ≤ CSnWCR2.WRON bit ≤ CSnWCR1.CSWWAIT bit.
3. Satisfy the following condition: CSnWCR2.WDOFF bit ≤ CSnWCR2.CSWOFF bit.

1.2.3 Recovery Cycles

The differences in the recovery cycle specifications are that in the M16C Family, recovery cycles are inserted before CS is negated, while in the RX Family, recovery cycles are inserted after CS is negated.

In the RX Family, 1 to 15 recovery cycles can be inserted. The condition for inserting a recovery cycle can be selected from the following:

- After a read access, the same external bus area is read accessed.
- After a read access, the same external bus area is write accessed.
- After a read access, a different external bus area is read accessed.
- After a read access, a different external bus area is write accessed.
- After a write access, the same external bus area is read accessed.
- After a write access, the same external bus area is write accessed.
- After a write access, a different external bus area is read accessed.
- After a write access, a different external bus area is write accessed

In the M16C Family, 1 to 3 recovery cycles can be inserted. When a recovery cycle is inserted, output for the data bus, address bus, and CS is extended.

2. Operating Modes Available

Table 2.1 shows Operating Modes Available for the External Bus.

Table 2.1 Operating Modes Available for the External Bus

No.	Operating Example	M16C (M16C/65C)	RX (RX231 or RX660)
		Mode	Mode
1	A program on the on-chip ROM reads data from external memory.	Memory expansion mode	On-chip ROM enabled extended mode
2	A program on external memory reads data from the external memory.	Microprocessor mode	On-chip ROM disabled extended mode

2.1 Device Operating Modes

The RX Family has three operating modes – single-chip mode, on-chip ROM enabled extended mode, and on-chip ROM disabled extended mode. Set the user program to enter each mode.

Table 2.2 Entering Modes in the RX Family *1

Mode	Program Setting
Single-chip mode	N/A
On-chip ROM enabled extended mode	Set the SYSCR0.ROME bit to 0b, and the SYSCR0.EXBE bit to 1b
On-chip ROM disabled extended mode	Set the SYSCR0.ROME bit to 1b, and the SYSCR0.EXBE bit to 1b *2

Notes: 1. Set the bus width in the CSn control register (CSnCR register).
2. Specify these register settings in an area other than the external memory and ROM.

The RX Family's on-chip ROM disabled extended mode differs from the M16C Family's processor mode, and requires a program to transition to the mode on the on-chip ROM.

The M16C Family has three processor modes – single-chip mode, memory expansion mode, and microprocessor mode. The pin and program must be set to enter each processor mode.

Table2.3 Entering Modes in the M16C Family *1

Mode	Mode Pin (CNVSS)	Program Setting
Single-chip mode	Low	N/A (when the MCU starts-up, bits PM01 and PM00 become 00b)
Memory expansion mode	Low	Set bits PM01 and PM00 to 01b *2
Microprocessor mode	High	N/A *3 (when the MCU starts-up, bits PM01 and PM00 become 11b)

Notes: 1. The bus width is set by the BYTE pin. Configure settings so the bus width is 8 bits when the BYTE pin is high, and 16 bits when the BYTE pin is low.
2. The bus must be set. Configure settings in accordance with the external memory.
3. The bus does not need to be set. Configure the bus when using a setting other than 1ϕ + 1ϕ for reading the external memory.

3. Differences in Operating Modes

Table 3.1 shows Functional Differences in the Operating Modes That Use the External Memory and On-Chip Memory (RX Family/M16C). Table 3.2 shows Functional Differences in the Operating Modes That Use Only the External Memory (RX Family/M16C).

Table 3.1 Functional Differences in the Operating Modes That Use the External Memory and On-Chip Memory (RX Family/M16C)

Item	M16C (M16C/65C)	RX (RX231)	RX (RX660)
	Memory Expansion Mode	On-chip ROM Enabled Extended Mode	On-chip ROM Enabled Extended Mode
Access area	SFRs, internal RAM, internal ROM, external areas	I/O registers, on-chip RAM, on-chip ROM, external areas	I/O registers, on-chip RAM, on-chip ROM, external areas
External memory area	Addresses 04000h to CFFFFh	0500 0000h to 07FF FFFFh (CS1, CS2, CS3)	05E0 0000h to 05FF FFFFh (CS3) 06E0 0000h to 06FF FFFFh (CS2) 07E0 0000h to 07FF FFFFh (CS1)

Table 3.2 Functional Differences in the Operating Modes That Use Only the External Memory (RX Family/M16C)

Item	M16C (M16C/65C)	RX (RX231)	RX (RX660)
	Microprocessor mode	On-chip ROM disabled extended mode	On-chip ROM disabled extended mode
Access area	SFRs, internal RAM, external areas	I/O registers, on-chip RAM, on-chip ROM *1, external areas	I/O registers, on-chip RAM, on-chip ROM *1, external areas
External memory area	Addresses 04000h to FFFFFh	0500 0000h to 07FF FFFFh (CS1, CS2, CS3) FF00 0000h to FFFF FFFFh (CS0)	05E0 0000h to 05FF FFFFh (CS3) 06E0 0000h to 06FF FFFFh (CS2) 07E0 0000h to 07FF FFFFh (CS1) FFE0 0000h to FFFF FFFFh (CS0)

Note: 1. Enabled at startup only

4. Appendix

4.1 Points on Migration From the M16C Family to the RX Family

This chapter explains points on migration from the M16C Family to the RX Family.

4.1.1 Interrupts

For the RX Family, when an interrupt request is received while all of the following conditions are met, the interrupt occurs.

- The I flag (PSW.I bit) is 1.
- Registers IER and IPR in the ICU are set to enable interrupts.
- The interrupt request is enabled by the interrupt request enable bits for peripheral functions.

Table 4.1 shows Comparison of Conditions for Interrupt Generation Between the RX and the M16C.

Table 4.1 Comparison of Conditions for Interrupt Generation Between the RX and the M16C

Item	M16C	RX
I flag	When the I flag is set to 1 (enabled), the maskable interrupt request can be accepted.	
Interrupt request flag	When an interrupt request is generated by a peripheral function, the interrupt request flag becomes 1 (interrupt requested).	
Interrupt priority level	Selected by setting bits ILVL2 to ILVL0.	Selected by setting the IPR[3:0] bits.
Interrupt request enable	—	Specified by setting the IER register.
Interrupt enable for peripheral functions	—	Interrupts can be enabled or disabled in each peripheral function.

For more information, refer to sections Interrupt Controller (ICU), CPU, and sections for other peripheral functions used in the User's Manual: Hardware.

4.1.2 I/O Ports

In the RX Family, the MPC must be configured in order to assign I/O signals from peripheral functions to pins.

Before controlling the I/O pins in the RX Family, the following two items must be set.

- In the MPC.PFS register, select the peripheral functions that are assigned to the appropriate pins.
- In the PMR register for I/O ports, select the function for the pin to be used as a general I/O port or I/O port for a peripheral function.

Table 4.2 shows Comparison of I/O Settings for Peripheral Function Pins Between the RX and the M16C.

Table 4.2 Comparison of I/O Settings for Peripheral Function Pins Between the RX and the M16C

Function	M16C (in the case of the M16C/65C)	RX (in the case of the RX660/RX231)
Select the pin function	These are not available in the M16C. *1 When a mode is set for a peripheral function, appropriate pins are assigned as I/O pins for the peripheral function.	With the PFS register, I/O ports for peripheral functions can be assigned by selecting from multiple pins.
Switch between general I/O port and peripheral function		With the PMR register, the corresponding pin function can be selected as a general I/O port or a peripheral function.

Note: 1. Register for similar functions are available in the M32C Series and R32C Series.

For more information, refer to the Multi-Function Pin Controller (MPC) and I/O port sections in the User's Manual: Hardware.

4.1.3 Module Stop Function

The RX Family has the ability to stop each peripheral module individually.

By transitioning unused peripheral modules to the module stop state, power consumption can be reduced.

After a reset is released, all modules (with a few exceptions) are in the module stop state.

Registers for modules in the module stop state cannot be written to or read.

For more information, refer to the Low Power Consumption section in the User's Manual: Hardware.

4.2 I/O Register Macros

Macro definitions listed in Table 4.3 can be found in the RX I/O register definitions (iodefine.h).

The readability of programs can be achieved with these macro definitions.

Table 4.3 shows Macro Usage Examples.

Table 4.3 Macro Usage Examples

Macro	Usage Example
IR("module name", "bit name")	**IR(MTU0, TGIA0)** = 0 ; The IR bit corresponding to MTU0.TGIA0 is cleared to 0 (no interrupt request is generated).
DTCE("module name", "bit name")	**DTCE (MTU0, TGIA0)** = 1 ; The DTCE bit corresponding to MTU0.TGIA0 is set to 1 (DTC activation is enabled).
IEN("module name", "bit name")	**IEN(MTU0, TGIA0)** = 1 ; The IEN bit corresponding to MTU0.TGIA0 is set to 1 (interrupt enabled).
IPR("module name", "bit name")	**IPR(MTU0, TGIA0)** = 0x02 ; The IPR bit corresponding to MTU0.TGIA0 is set to 2 (interrupt priority level 2).
MSTP("module name")	**MSTP(MTU)** = 0 ; The MTU0 Module Stop bit is set to 0 (module stop state is canceled).
VECT("module name", "bit name")	#pragma interrupt (Excep_MTU0_TGIA0 (vect = **VECT(MTU0, TGIA0)**) The interrupt function is declared for the corresponding MTU0.TGIA0 register.

4.3 Intrinsic Functions

The RX Family has intrinsic functions for setting control registers and special instructions. When using intrinsic functions, include machine.h.

Table 4.4 shows Examples of Differences in the Settings of Control Registers and Descriptions of Special Instructions Between the RX and the M16C.

Table 4.4 Examples of Differences in the Settings of Control Registers and Descriptions of Special Instructions Between the RX and the M16C

Item	Description	
	M16C	**RX**
Set the I flag to 1	asm("fset i");	setpsw_i (); *1
Set the I flag to 0	asm("fclr i");	clrpsw_i (); *1
Expanded into the WAIT instruction	asm("wait");	wait(); *1
Expanded into the NOP instruction	asm("nop");	nop(); *1

Note: 1. The machine.h file must be included.

5. Reference Documents

User's Manual: Hardware

RX230/RX231 Group User's Manual: Hardware (R01UH0496EJ)
RX660 Group User's Manual: Hardware (R01UH0037EJ)
M16C/65C Group User's Manual: Hardware (R01UH0093EJ)
If you are using a product that does not belong to the RX231, RX660, or M16C/65C Group, refer to the applicable user's manual for hardware.
The latest versions can be downloaded from the Renesas Electronics website.

Technical Update/Technical News

The latest information can be downloaded from the Renesas Electronics website.

User's Manual: Development Tools

RX Family CC-RX Compiler User's Manual (R20UT3248)
M16C Series, R8C Family C Compiler Package (M3T-NC30WA)
The latest versions can be downloaded from the Renesas Electronics website.

REVISION HISTORY

Rev.	Date	Description	
		Page	Summary
1.00	Sep. 1, 2014	—	First edition issued
2.00	June 12, 2023	—	The product model of the target device for the RX MCU was changed: From RX210 to RX231/RX660

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

   A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.
2. Processing at power-on

   The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.
3. Input of signal during power-off state

   Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.
4. Handling of unused pins

   Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.
5. Clock signals

   After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.
6. Voltage application waveform at input pin

   Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).
7. Prohibition of access to reserved addresses

   Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.
8. Differences between products

   Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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